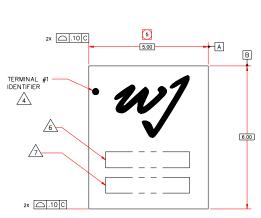
Outline Drawing



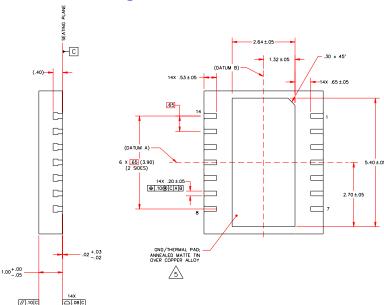
NOTES:

- EXCEPT WHERE NOTED, THIS PART OUTLINE CONFORMS TO JEDEC STANDARD MO-229, ISSUE C (VARIATION VJGC) FOR THERMALLY ENHANCED PLASTIC VERY THIN FINE PITCH QUAD FLAT NO LEAD PACKAGE (QFN).
- 2. DIMENSIONING & TOLERANCING CONFORM TO ASME Y14.4M-1994.
- 3. ALL DIMENSIONS ARE IN MILLIMETERS. ANGLES ARE IN DEGREES.

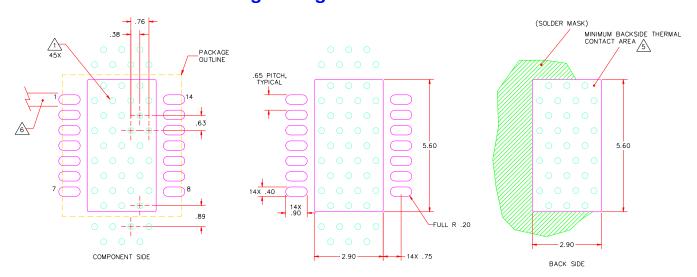
THE TERMINAL #1 IDENTIFIER AND TERMINAL NUMBERING CONVENTION CONFORM TO JESD 95-1 SPP-012.

5 COPLANARITY APPLIES TO THE EXPOSED GROUND/THERMAL PAD AS WELL AS THE TERMINALS.

6 PART NUMBER



Mounting Configuration / Land Pattern



NOTES:

GROUND/THERMAL VIAS ARE CRITICAL FOR THE PROPER PERFORMANCEOF THIS DEVICE. VIAS SHOULD USE A .35mm (#80/.0135") DIAMETER DRILL AND HAVE A FINAL, PLATED THRU DIAMETER OF .25mm (.010").

- 2. ADD AS MUCH COPPER AS POSSIBLE TO INNER AND OUTER LAYERS NEAR THE PART TO ENSURE OPTIMAL THERMAL PERFORMANCE.
- ADD AS MUCH COPPER AS POSSIBLE TO INNER AND OUTER LAYERS NEAR THE PART TO ENSURE OPTIMA
 TO ENSURE RELIABLE OPERATION, DEVICE GROUND PADDLE-TO-GROUND PAD SOLDER JOINT IS CRITICAL.
- 4. ADD MOUNTING SCREWS NEAR THE PART TO FASTEN THE BOARD TO A HEATSINK. ENSURE THAT THE GROUND/THERMAL VIA REGION CONTACTS THE HEATSINK.

DO NOT PUT SOLDER MASK ON THE BACK SIDE OF THE PC BOARD IN THE REGION WHERE THE BOARD CONTACTS THE HEATSINK.

 $\stackrel{\textstyle \frown}{6}$ RF TRACE WIDTH DEPENDS UPON THE PC BOARD MATERIAL AND CONSTRUCTION.

- 7. USE 1 OZ. COPPER MINIMUM.
- 8. ALL DIMENSIONS ARE IN MILLIMETERS. ANGLES ARE IN DEGREES.
- A HEATSINK UNDERNEATH THE AREA OF THE PCB FOR THE MOUNTED DEVICE IS STRICTLY REQUIRED FOR PROPER THERMAL OPERATION.
 DAMAGE TO THE DEVICE CAN OCCUR WITHOUT THE USE OF ONE.